

CesiStar Series

AOI Inspection Machine

星准系列AOI检测机



Go tech! Go core!
让智慧改变芯未来

CesiStar Series AOI Inspection Machine

星准系列AOI检测机



星准系列 AOI 检测机是利用光学原理检测芯片缺陷的高速高精度全自动视觉检测设备,主要应用于芯片封装的研发与制造。针对 BGA, LGA, QFN, QFP 等多种封装芯片,提供全面的6-side 检测和2D/3D量测。

应用行业

Application industries

半导体、消费类电子、汽车电子等

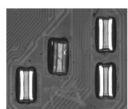
设备特点

Product features

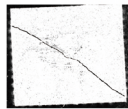
- **高精度**
3D 测量精度 $5\mu\text{m}$;支持 $100\mu\text{m}$ BGA Balls,支持Surface dents, bulges检测
- **高Throughput**
UPH Up to 40k(QFN 5X5)
- **高适配性**
兼容 BGA,QFN,LGA,QFP,SOP 等多种芯片封装形式;
覆盖 $3\times 3\text{mm}$ ~ $120\times 120\text{mm}$ 芯片尺寸
- **易用性**
快速换型时间

缺陷检测

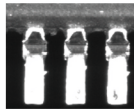
Defect detection



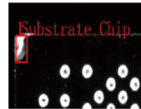
电容损坏



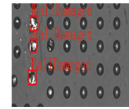
裂纹



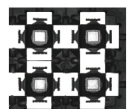
毛刺



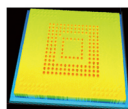
崩边



球损坏



5-side



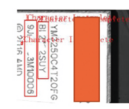
3D测量



异色



漏铜



印字检测

设备参数

Product specifications

■ 即将上市/In Development ■ 可选配置/Optional

产品型号	IR9821	IR9822	IR9721/IS9721
出入料	Tray to Tray	Tray to Tray	Tray to Tray/Tray to Reel
芯片尺寸	3×3mm~50×50mm	3×3mm~58×58mm	3×3mm~120×120mm
最小球径	100μm	100μm	150μm
表面检测能力	30x30μm	30x30μm	50x50μm
3D精度	5μm	5μm	7.5μm
20μm球高检测	Avaliable	Avaliable	Avaliable
表面凹坑检测	Avaliable(Bottom only)	Avaliable(Bottom + Top)	Avaliable(Bottom only)
分选	1x4 Head	1x4 Head	1x4 Head
色彩检测 (选配)	Avaliable	Avaliable	Avaliable
芯片厚度检测 (选配)	Avaliable	Avaliable	Avaliable
二维码读取	Avaliable	Avaliable	Avaliable
字符识别	Avaliable	Avaliable	Avaliable
裂纹检测	10μm width	10μm width	15μm width
UPH	2500(PKG35X35 BGA)	3500(PKG35X35)	3500(PKG35X35)
	11K(PKG5*5 QFN 5S)	14K(PKG5*5 QFN 5S)	14K(PKG5*5 QFN 5S)
	21K(PKG5*5 QFN)	30K(PKG5*5 QFN)	40K(PKG5*5 QFN)

以上图片及参数仅供参考,实际以技术协议为准。

The pictures and parimeters above are for reference,Final details will be reflected in our technical agreement.



博众半导体公众号



博众半导体视频号

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